

BFR720L3RH

NPN Silicon Germanium RF Transistor

Target data sheet

- High gain ultra low noise RF transistor for low current operation
- Provides outstanding performance for a wide range of wireless applications up to 10 GHz and more
- Optimum gain and noise figure at low current operation
- Ideal for WLAN applications
- Outstanding noise figure F = 0.5 dB at 1.8 GHz
 Outstanding noise figure F = 0.8 dB at 6 GHz
- High maximum stable and available gain G_{ms} = 24 dB at 1.8 GHz, G_{ma} = 16.5 dB at 6 GHz
- 150 GHz f_T-Silicon Germanium technology
- Extremly small and flat leadless package height 0.32 mm max.
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BFR720L3RH	R3	1 = B	2 = C	3 = E	TSLP-3-9





Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CEO}		V
<i>T</i> _A > 0 °C		4	
$T_{A} \leq 0 ^{\circ}C$		3.5	
Collector-emitter voltage	V _{CES}	13	
Collector-base voltage	V _{CBO}	13	
Emitter-base voltage	V _{EBO}	1.2	
Collector current	I _C	20	mA
Base current	I _B	2	
Total power dissipation ¹⁾	P _{tot}	80	mW
$T_{S} \leq tbd$			
Operating junction temperature range	T _{io}	-65 150	°C
Storage junction temperature range	Tistg	-65 150	
Thermal Resistance			

ParameterSymbolValueUnitJunction - soldering point2) R_{thJS} \leq tbdK/W

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	V _{(BR)CEO}	4	4.7	-	V
<i>I</i> _C = 1 mA, <i>I</i> _B = 0					
Collector-emitter cutoff current	I _{CES}	-	-	30	μA
$V_{\rm CE}$ = 13 V, $V_{\rm BE}$ = 0					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{\rm CB} = 5 \text{ V}, I_{\rm E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	2	μA
$V_{\rm EB}$ = 0.5 V, $I_{\rm C}$ = 0					
DC current gain-	h _{FE}	160	250	400	-
$I_{\rm C}$ = 13 mA, $V_{\rm CE}$ = 3 V, pulse measured					

 ${}^{1}T_{S}$ is measured on the collector lead at the soldering point to the pcb

²For calculation of $R_{\rm thJA}$ please refer to Application Note Thermal Resistance



Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
AC Characteristics (verified by random sampling	ļ)			-	
Transition frequency	f _T	-	45	-	GHz
<i>I</i> _C = 13 mA, <i>V</i> _{CE} = 3 V, <i>f</i> = 1 GHz					
Collector-base capacitance	C _{cb}	-	0.07	-	pF
$V_{CB} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
emitter grounded					
Collector emitter capacitance	C _{ce}	-	0.26	-	
$V_{CE} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
based grounded					
Emitter-base capacitance	C _{eb}	-	0.27	-	
$V_{\rm EB}$ = 0.5 V, f = 1 MHz, $V_{\rm CB}$ = 0 ,					
collector grounded					
Noise figure	NF				dB
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, f = 1.8 GHz, $Z_{\rm S}$ = $Z_{\rm Sopt}$		-	0.5	-	
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, f = 6 GHz, $Z_{\rm S}$ = $Z_{\rm Sopt}$		-	0.8	-	
Power gain ¹⁾	G _{ms}	-	24	-	dB
$I_{\rm C}$ = 13 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{\rm L} = Z_{\rm Lopt}, f = 1.8 {\rm GHz}$					
Power gain, maximum available ¹⁾	G _{ma}	-	16.5	-	dB
$I_{\rm C}$ = 13 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{\rm L} = Z_{\rm Lopt}, f = 6 {\rm GHz}$					
Transducer gain	S _{21e} ²				dB
$I_{\rm C}$ = 13 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω ,					
<i>f</i> = 1.8 GHz		-	22	-	
<i>f</i> = 6 GHz		-	13.5	-	
Third order intercept point at output ²⁾	IP ₃	-	20.5	-	dBm
V_{CE} = 3 V, I_{C} = 10 mA, Z_{S} = Z_{L} =50 Ω , f = 1.8 GHz					
1dB Compression point	P _{-1dB}	-	6	-	
$I_{\rm C}$ = 13 mA, $V_{\rm CF}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm L}$ =50 Ω , f = 1.8 GHz					

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

 ${}^{1}G_{ma} = |S_{21e} / S_{12e}| (k - (k^{2} - 1)^{1/2}), G_{ms} = |S_{21e} / S_{12e}|$

²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50 Ω from 0.1 MHz to 6 GHz







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